FSL

PRODUCT AND PROCESS CHANGE NOTIFICATION

Generic Copy

ISSUE DATE: 06-Feb-2014

NOTIFICATION: 16023

TITLE: MC9S08QG8 & MC9S08SH8 Assembly Transfer from STATS Chippac to FSL-TJN-FM Facility

EFFECTIVE DATE: 15-May-2014

DEVICE(S)

MPN
MC9S08QA2CFQE
MC9S08QA4CFQE
MC9S08QG4CFFE
MC9S08QG4CFFER
MC9S08QG4CFKE
MC9S08QG4CFQE
MC9S08QG8CFFE
MC9S08QG8CFFER
MC9S08QG8CFKE
MC9S08QG8CFQE
MC9S08QG8MFFE
MC9S08QG8MFQE
MC9S08SH4CFK
MC9S08SH8CFK

AFFECTED CHANGE CATEGORIES

- ASSEMBLY SITE

DESCRIPTION OF CHANGE

Freescale Semiconductor is announcing the assembly site transfer for the products listed in this notification, from the current STATS Chippac, Kuala Lumpur, Malaysia, assembly Facility to the FSL-TJN-FM, Tianjin, China assembly Facility, which is being qualified as assembly site for the products listed in notification.

REASON FOR CHANGE

Current assembly site STATS Chippac, Kuala Lumpur, Malaysia will close, Qualification of Freescale Semiconductor Tianjin, China, assembly Facility to continue customer support.

ANTICIPATED IMPACT OF PRODUCT CHANGE(FORM, FIT, FUNCTION, OR RELIABILITY)

There is no impact on device form, fit, function or reliability.

Freescale will consider specific conditions of acceptance of this change submitted within 30 days of receipt of this notice on a case by case basis. To request further data or inquire about the notification, please enter a **Service Request.**

For sample inquiries - please go to www.freescale.com

QUAL DATA AVAILABILITY DATE: 29-Mar-2014

QUALIFICATION STATUS: IN PROCESS

QUALIFICATION PLAN:

Freescale Semiconductor Manufacturing standard specification for assembly transfers was followed for the Assembly Transfer.

RELIABILITY DATA SUMMARY:

Will provide per request.

ELECTRICAL CHARACTERISTIC SUMMARY:

Comparison between STATS Chippac, Kuala Lumpur, Malaysia and Freescale FSL-TJN-FM, Tianjin, China will be completed. Report will be provided on request.

CHANGED PART IDENTIFICATION:

For both 4X4 QFN and 5X5 QFN, the assembly site, among other information, is reflected in the package trace code.

The format for the Freescale standard trace code: ALYWZ is the following:

A=Assembly Site, L=Wafer Lot, Y=Year, W=Work Week,Z=Z CODE.

The current assembly site marking for STATS Chippac is A=RH.

The marking for proposed assembly site FSL-TJN-FM is A=4.

Leadframe drawing change in databook please refer to attached file.

SAMPLE AVAILABILITY DATE: 14-Feb-2014

ATTACHMENT(S):
External attachment(s) FOR this notification can be viewed AT:
16023_MC9S08QG8_&_MC9S08SH8_Case_outline_Summary.pdf